

# BCM856BS; BCM856BS/DG BCM856DS; BCM856DS/DG

PNP/PNP matched double transistors

Rev. 01 — 7 August 2008

Product data sheet

## 1. Product profile

### 1.1 General description

PNP/PNP matched double transistors in small Surface-Mounted Device (SMD) plastic packages. The transistors are fully isolated internally.

Table 1. Product overview

Type number	Package		Package configuration
	NXP	JEITA	
BCM856BS BCM856BS/DG	SOT363	SC-88	very small
BCM856DS BCM856DS/DG	SOT457	SC-74	small

### 1.2 Features

- Current gain matching
- Base-emitter voltage matching
- Drop-in replacement for standard double transistors
- AEC-Q101 qualified

### 1.3 Applications

- Current mirror
- Differential amplifier

### 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$V_{CE0}$	collector-emitter voltage	open base	-	-	-65	V
$I_C$	collector current		-	-	-100	mA
$h_{FE}$	DC current gain	$V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$	200	290	450	



**Table 2. Quick reference data ...continued**

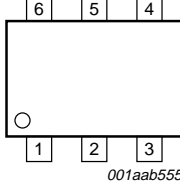
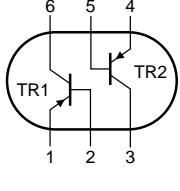
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per device</b>						
$h_{FE1}/h_{FE2}$	$h_{FE}$ matching	$V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$	[1] 0.9	1	-	
$V_{BE1}-V_{BE2}$	$V_{BE}$ matching	$V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$	[2] -	-	2	mV

[1] The smaller of the two values is taken as the numerator.

[2] The smaller of the two values is subtracted from the larger value.

## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1	emitter TR1	 <p>001aab555</p>	 <p>sym018</p>
2	base TR1		
3	collector TR2		
4	emitter TR2		
5	base TR2		
6	collector TR1		

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
BCM856BS	SC-88	plastic surface-mounted package; 6 leads	SOT363
BCM856BS/DG			
BCM856DS	SC-74	plastic surface-mounted package (TSOP6); 6 leads	SOT457
BCM856DS/DG			

## 4. Marking

**Table 5. Marking codes**

Type number	Marking code <sup>[1]</sup>
BCM856BS	*BS
BCM856BS/DG	PB*
BCM856DS	DS
BCM856DS/DG	R9

[1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

## 5. Limiting values

**Table 6. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
<b>Per transistor</b>					
$V_{CBO}$	collector-base voltage	open emitter	-	-80	V
$V_{CEO}$	collector-emitter voltage	open base	-	-65	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$I_C$	collector current		-	-100	mA
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C			
	BCM856BS (SOT363) BCM856BS/DG (SOT363)		[1]	- 200	mW
	BCM856DS (SOT457) BCM856DS/DG (SOT457)		[1]	- 250	mW
<b>Per device</b>					
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C			
	BCM856BS (SOT363) BCM856BS/DG (SOT363)		[1]	- 300	mW
	BCM856DS (SOT457) BCM856DS/DG (SOT457)		[1]	- 380	mW
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-55	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 7. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	BCM856BS (SOT363) BCM856BS/DG (SOT363)		[1]	-	625	K/W
	BCM856DS (SOT457) BCM856DS/DG (SOT457)		[1]	-	500	K/W
<b>Per device</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air				
	BCM856BS (SOT363) BCM856BS/DG (SOT363)		[1]	-	416	K/W
	BCM856DS (SOT457) BCM856DS/DG (SOT457)		[1]	-	328	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

## 7. Characteristics

**Table 8. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -30\text{ V};$ $I_E = 0\text{ A}$	-	-	-15	nA
		$V_{CB} = -30\text{ V};$ $I_E = 0\text{ A};$ $T_j = 150\text{ }^{\circ}\text{C}$	-	-	-5	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V};$ $I_C = 0\text{ A}$	-	-	-100	nA
$h_{FE}$	DC current gain	$V_{CE} = -5\text{ V};$ $I_C = -10\text{ }\mu\text{A}$	-	250	-	
		$V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$	200	290	450	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -10\text{ mA};$ $I_B = -0.5\text{ mA}$	-	-50	-200	mV
		$I_C = -100\text{ mA};$ $I_B = -5\text{ mA}$	-	-200	-400	mV
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -10\text{ mA};$ $I_B = -0.5\text{ mA}$	[1]	-760	-	mV
		$I_C = -100\text{ mA};$ $I_B = -5\text{ mA}$	[1]	-920	-	mV

**Table 8. Characteristics ...continued**  
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

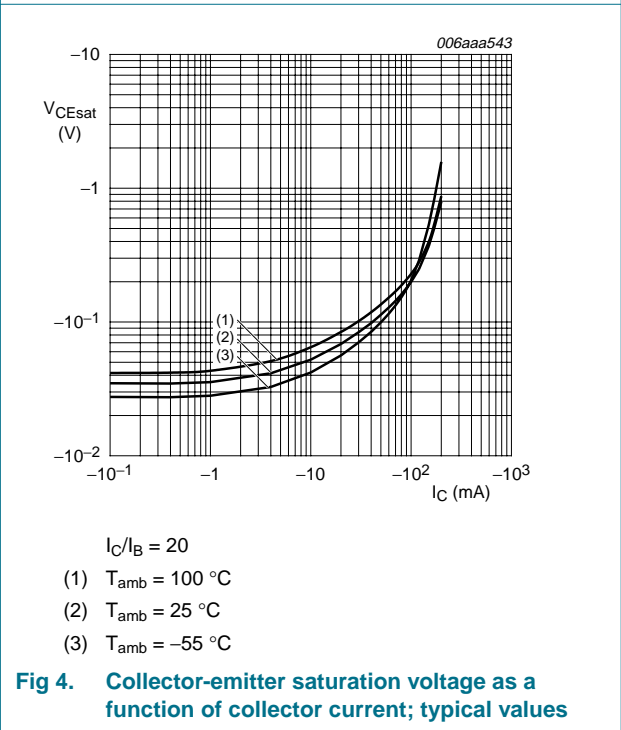
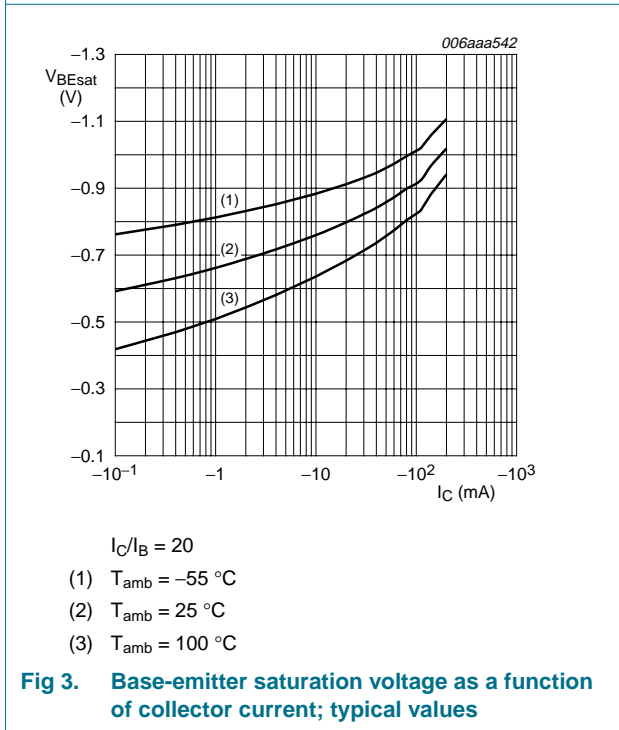
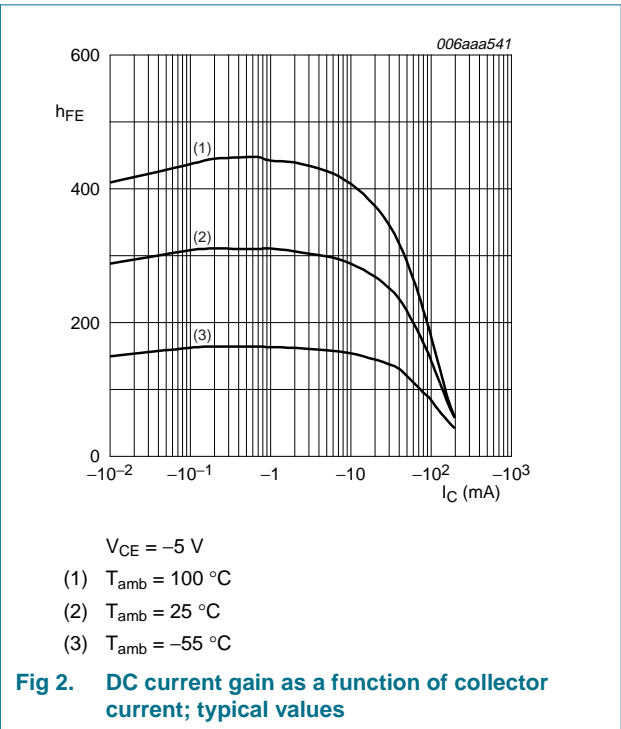
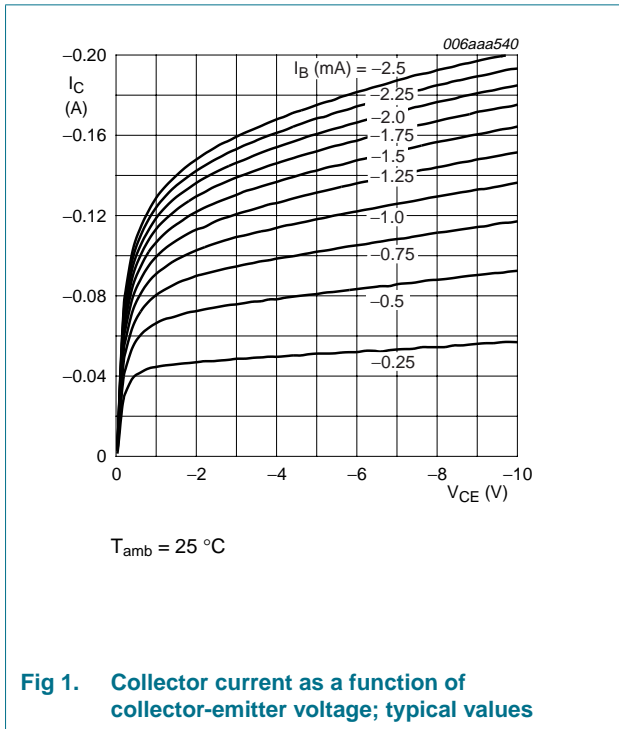
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{BE}$	base-emitter voltage	$V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$	[2] -600	-650	-700	mV
		$V_{CE} = -5\text{ V};$ $I_C = -10\text{ mA}$	[2] -	-	-760	mV
$C_c$	collector capacitance	$V_{CB} = -10\text{ V};$ $I_E = I_E = 0\text{ A};$ $f = 1\text{ MHz}$	-	-	2.2	pF
$C_e$	emitter capacitance	$V_{EB} = -0.5\text{ V};$ $I_C = I_C = 0\text{ A};$ $f = 1\text{ MHz}$	-	10	-	pF
$f_T$	transition frequency	$V_{CE} = -5\text{ V};$ $I_C = -10\text{ mA};$ $f = 100\text{ MHz}$	100	175	-	MHz
NF	noise figure	$V_{CE} = -5\text{ V};$ $I_C = -0.2\text{ mA};$ $R_S = 2\text{ k}\Omega;$ $f = 10\text{ Hz to}$ $15.7\text{ kHz}$	-	1.6	-	dB
		$V_{CE} = -5\text{ V};$ $I_C = -0.2\text{ mA};$ $R_S = 2\text{ k}\Omega;$ $f = 1\text{ kHz};$ $B = 200\text{ Hz}$	-	3.1	-	dB
<b>Per device</b>						
$h_{FE1}/h_{FE2}$	$h_{FE}$ matching	$V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$	[3] 0.9	1	-	
$V_{BE1}-V_{BE2}$	$V_{BE}$ matching	$V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$	[4] -	-	2	mV

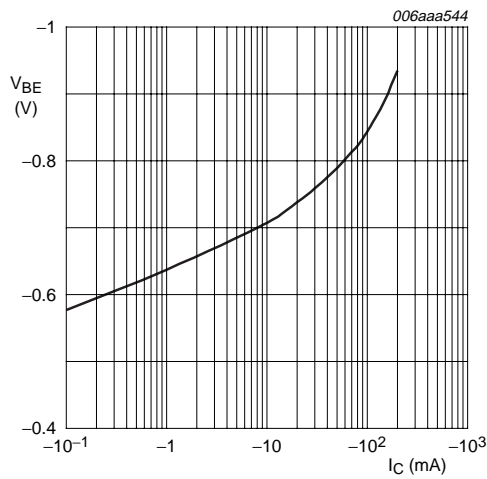
[1]  $V_{BEsat}$  decreases by about 1.7 mV/K with increasing temperature.

[2]  $V_{BE}$  decreases by about 2 mV/K with increasing temperature.

[3] The smaller of the two values is taken as the numerator.

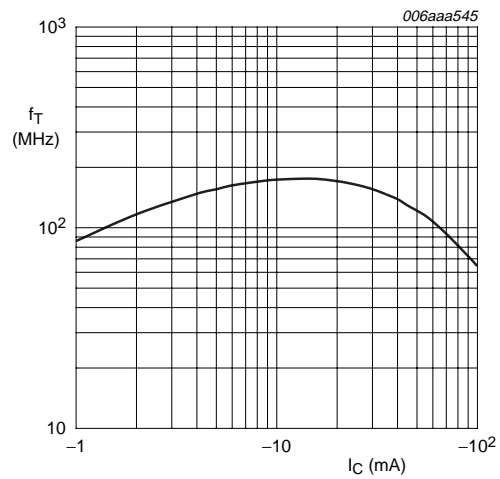
[4] The smaller of the two values is subtracted from the larger value.





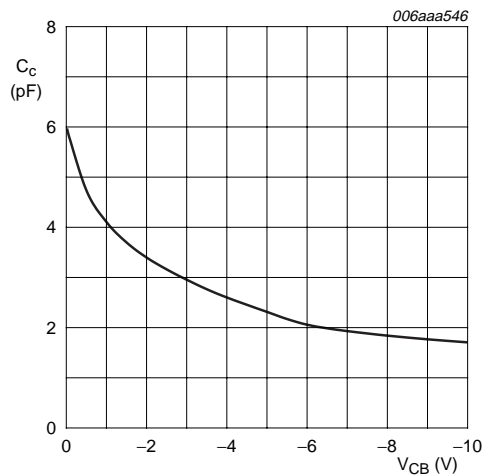
$V_{CE} = -5$  V;  $T_{amb} = 25$  °C

**Fig 5. Base-emitter voltage as a function of collector current; typical values**



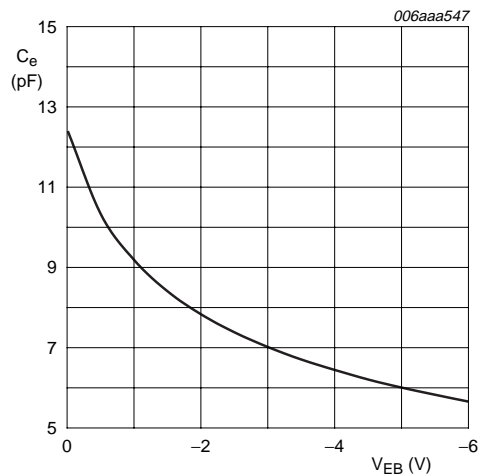
$V_{CE} = -5$  V;  $T_{amb} = 25$  °C

**Fig 6. Transition frequency as a function of collector current; typical values**



$f = 1$  MHz;  $T_{amb} = 25$  °C

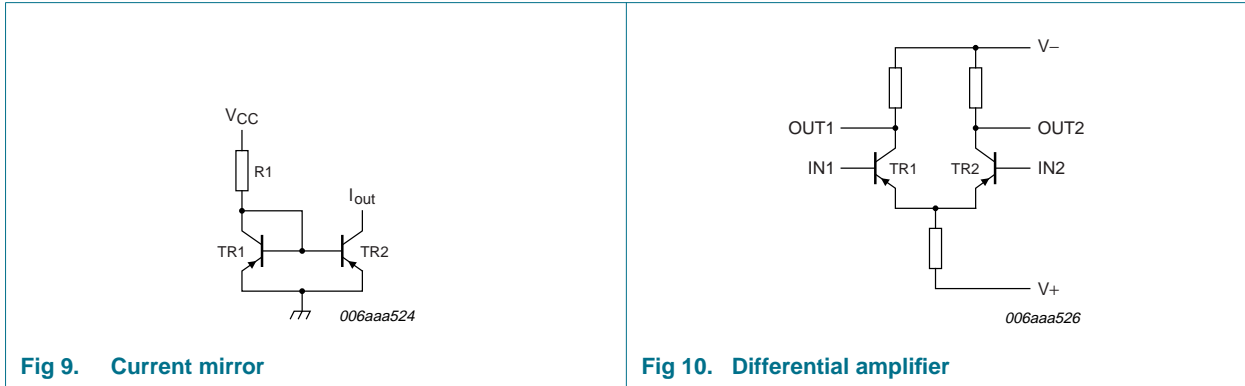
**Fig 7. Collector capacitance as a function of collector-base voltage; typical values**



$f = 1$  MHz;  $T_{amb} = 25$  °C

**Fig 8. Emitter capacitance as a function of emitter-base voltage; typical values**

## 8. Application information

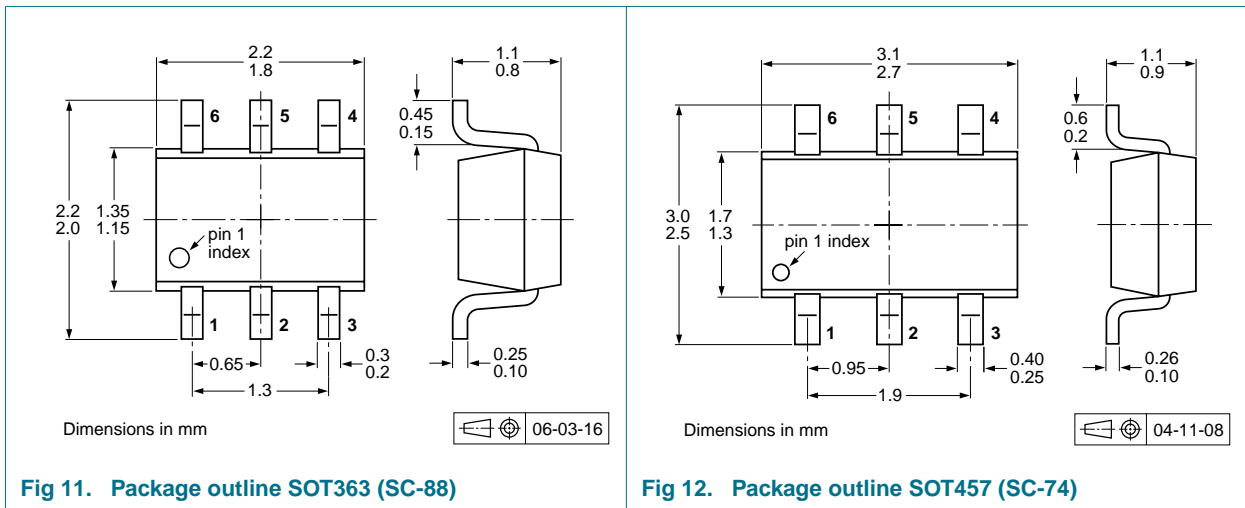


## 9. Test information

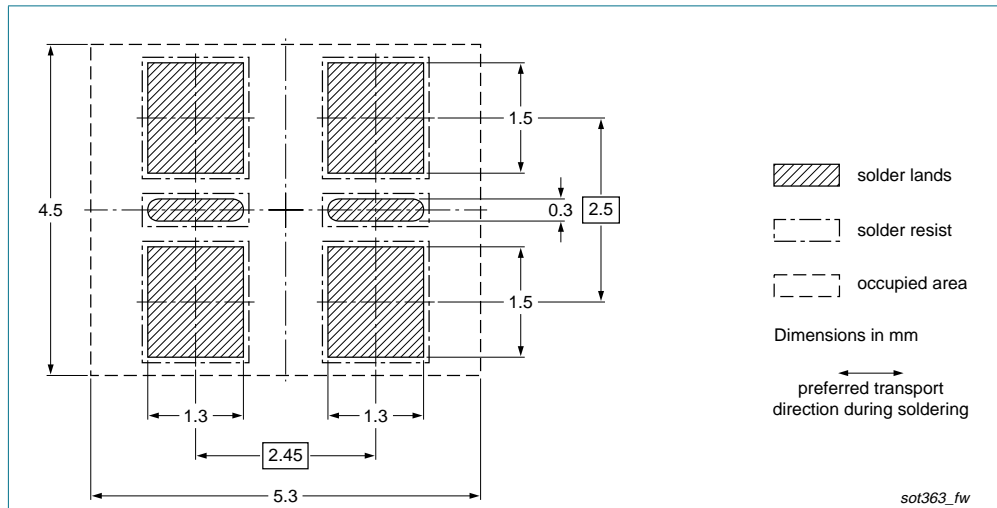
### 9.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

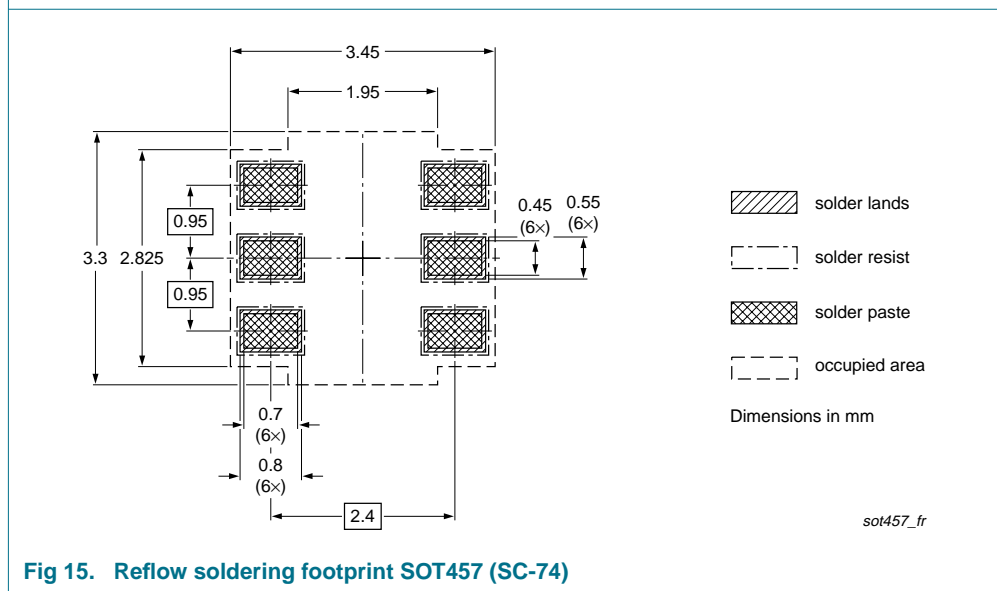
## 10. Package outline







**Fig 14. Wave soldering footprint SOT363 (SC-88)**



**Fig 15. Reflow soldering footprint SOT457 (SC-74)**

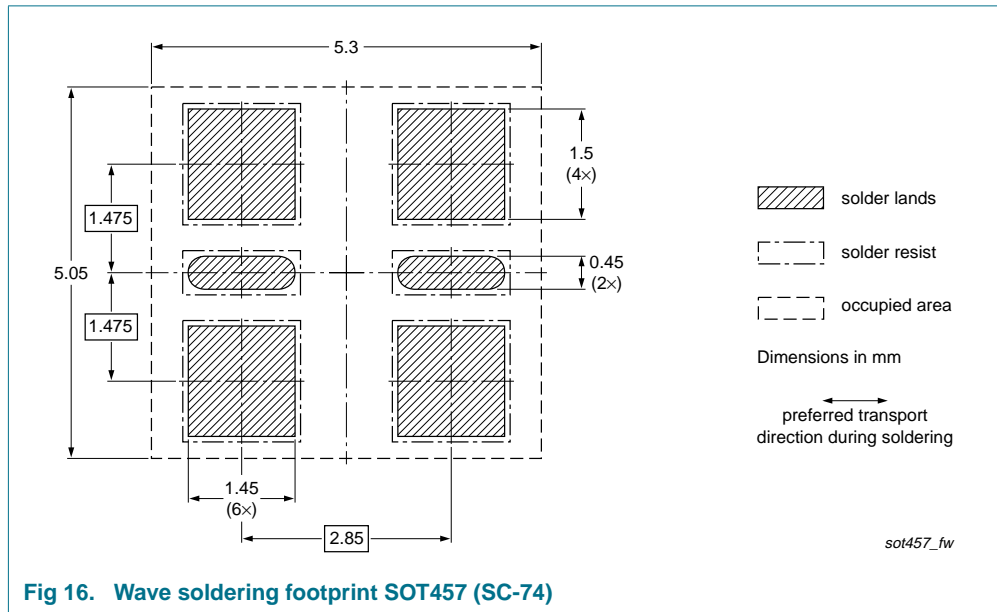


Fig 16. Wave soldering footprint SOT457 (SC-74)

## 13. Revision history

**Table 10. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BCM856BS_BCM856DS_1	20080807	Product data sheet	-	-

## 14. Legal information

### 14.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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**16. Contents**

<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description. . . . .	1
1.2	Features . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data. . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>2</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Marking</b> . . . . .	<b>3</b>
<b>5</b>	<b>Limiting values</b> . . . . .	<b>3</b>
<b>6</b>	<b>Thermal characteristics</b> . . . . .	<b>4</b>
<b>7</b>	<b>Characteristics</b> . . . . .	<b>4</b>
<b>8</b>	<b>Application information</b> . . . . .	<b>8</b>
<b>9</b>	<b>Test information</b> . . . . .	<b>8</b>
9.1	Quality information . . . . .	8
<b>10</b>	<b>Package outline</b> . . . . .	<b>8</b>
<b>11</b>	<b>Packing information</b> . . . . .	<b>9</b>
<b>12</b>	<b>Soldering</b> . . . . .	<b>9</b>
<b>13</b>	<b>Revision history</b> . . . . .	<b>12</b>
<b>14</b>	<b>Legal information</b> . . . . .	<b>13</b>
14.1	Data sheet status . . . . .	13
14.2	Definitions . . . . .	13
14.3	Disclaimers . . . . .	13
14.4	Trademarks . . . . .	13
<b>15</b>	<b>Contact information</b> . . . . .	<b>13</b>
<b>16</b>	<b>Contents</b> . . . . .	<b>14</b>

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